

DF Series

Indoor Fixed COB Panel


FCOB

Flip-Chip on Board

LED Chip

PCB

Specifications

Model	DF1.5	DF1.9
Pixel Pitch Exhibited(mm)	1.58	1.9
LED Type	COB (Flip chip)	COB (Flip chip)
Module Size(WxH)	304×342	304×342
Pixel Per Module(dots)	192×216	160×180
Panel Size(mm)	608×342×37/608×684×40	608×342×37/608×684×40
Pixel Per Panel(dots)	384×216/384×432	320×180/320×360
Material	Die casting aluminum	Die casting aluminum
Weight(kg/panel)	5.2/10	5.2/10
Brightness(nits)	1500	1000
Gray scale (bit)	13	13
Refresh rate (Hz)	4560	3900
Color Temperature(K)	3200~9300	3200~9300
Viewing angle(H)	170°	170°
Viewing angle(V)	160°	160°
Power Max. (W/m²)	330	250
Operating Temperature(°C)	-10~+45	-10~+45
Module IP Rating (Front)	IP65	IP65
Installation/Maintenance	Front	Front

Remark: Power consumption tolerance: ±15%, according to the actual situation.
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Integrated Cabinet

The integrated cabinet results in good tightness and high overall protection



Energy Saving

Reduce the loss and save the resources



Module Blackening Processing

Significantly improve black color consistency and enhance contrast



High Brightness

The maximum brightness can reach 1500 nits to meet the requirements of different application scenarios



Light and Thin

Cabinet thickness is only 37mm, making transportation and installation more convenient



Aluminum Bottom Shell



Module with aluminum bottom shell for superior cooling and radiation protection



Equipped with a safety rope for ensured security



Higher strength and splicing accuracy